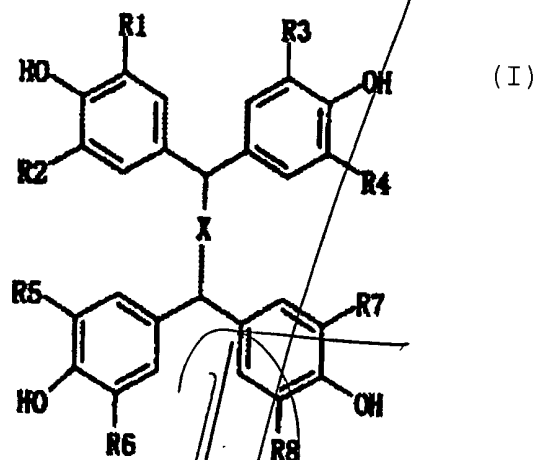


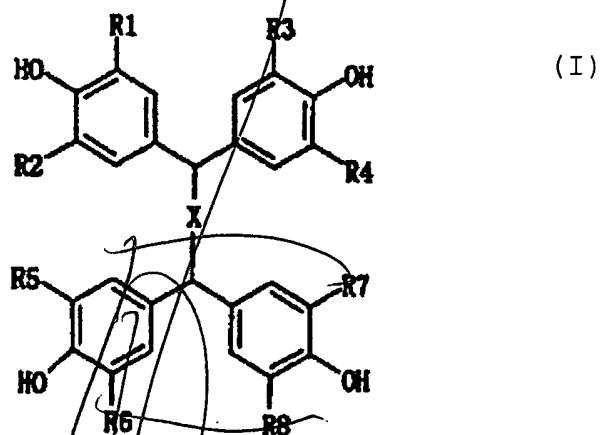
NEW CLAIMS

6. Epoxy resin compositions characterized by containing a curative which reacts with the epoxy group of an epoxy resin to cure the resin and a tetrakisphenol compound represented by a general formula (I):



wherein X represents $(CH_2)_n$, n is 0, 1, 2, or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, optionally-substituted phenyl, halogeno or a lower alkoxy, in an amount of from 0.001 to 0.1 mole based on 1 mole of the epoxy groups.

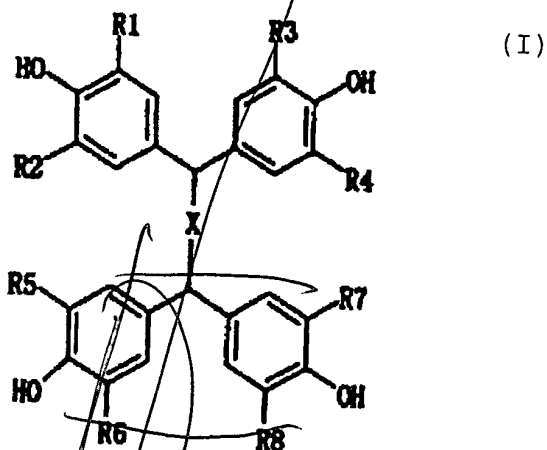
7. Curatives for epoxy resins characterized by being a clathrate comprising a tetrakisphenol compound represented by a general formula (I):



wherein X represents $(CH_2)_n$, n is 0, 1, 2, or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, optionally-substituted phenyl, halogeno or a lower alkoxy; and

a compound which reacts with the epoxy group of an epoxy resin to cure the resin.

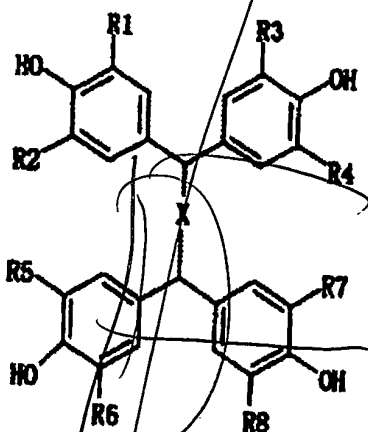
8. A curing accelerator for epoxy resins characterized by being a clathrate comprising a tetrakisphenol compound represented by a general formula (I):



wherein X represents $(CH_2)_n$, n is 0, 1, 2, or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, optionally-substituted phenyl, halogeno or a lower alkoxy; and

a compound accelerating the curing of a compound which reacts with the epoxy group of an epoxy resin to cure the resin.

9. A clathrate curing accelerator for epoxy resins comprising:
 a tetrakisphenol compound represented by a general formula (I):

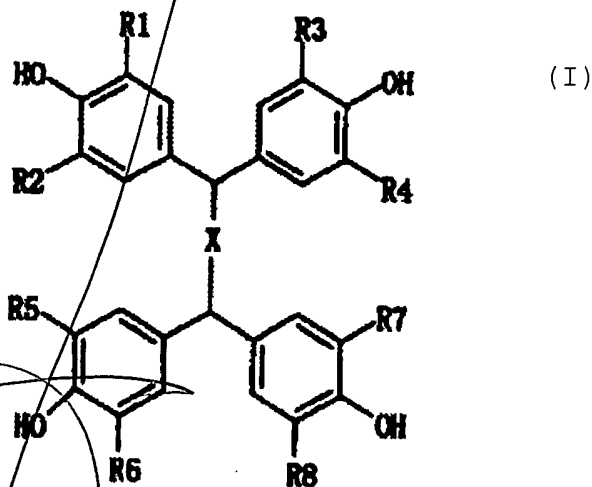


(I)

wherein X represents $(CH_2)_n$, n is 0, 1, 2, or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, optionally-substituted phenyl, halogeno or a lower alkoxy; and

a compound other than the tetrakisphenol compound, which accelerates the curing of an epoxy resin, wherein the clathrate is present in the resin in a range of from 0.001 to 0.1 mole based on 1 mole of the epoxy groups.

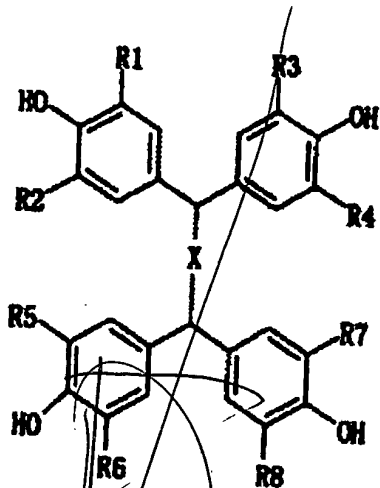
10. Epoxy resin compositions comprising:
 an epoxy resin, said epoxy resin containing a clathrate
 curative, said clathrate curative being a tetrakisphenol compound
 represented by a general formula (I):



wherein X represents $(CH_2)_n$, n is 0, 1, 2, or 3, and R^1 to R^8
 each represents hydrogen, a lower alkyl, optionally-substituted
 phenyl, halogen or a lower alkoxy; and

a compound other than the tetrakisphenol compound, which
 reacts with epoxy groups of the epoxy resin to cure the resin,
 wherein the clathrate curative is present in the resin in a range
 of from 0.001 to 0.1 mole based on 1 mole of the epoxy groups;
 and/or

a clathrate curing accelerator, said clathrate curing
 accelerator being a tetrakisphenol compound represented by a
 general formula (I):



(I)

wherein X represents $(CH_2)_n$, wherein n is 0, 1, 2, or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, optionally-substituted phenyl, halogeno or a lower alkoxy; and

a compound other than the tetrakisphenol compound, which accelerates the curing of an epoxy resin, wherein the clathrate is present in the resin in a range of from 0.001 to 0.1 mole based on 1 mole of the epoxy groups.